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Attorney's Pocket No. 5051-575

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Franzon et al.
Serial No.: 09/997,586
Filed: November 28, 2001
For: BURIED SOLDER BUMPS FOR AC-COUPLED MICROELECTRONIC
INTERCONNECTS

Confirmation No.: 6227
Group Art Unit: 2833
Examiner: Edwin A. Leon

August 29, 2002

Commissioner for Patents
Washington, DC 20231

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

Attached is a form PTO-1449, together with a copy of the identified document(s). This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(b), within three months of the filing date of the above-referenced application or before the mailing of a first Office Action on the merits, whichever event occurs last. Accordingly, no fee is required. The Commissioner is authorized to charge any additional fee, or credit any refund, to our Deposit Account No. 50-0220.

Respectfully submitted,

Mitchell S. Bigel
Registration No. 29,614

USPTO Customer No. 20792
Myers Bigel Sibley & Sajovec
Post Office Box 37428
Raleigh, North Carolina 27627
Telephone (919) 854-1400
Facsimile (919) 854-1401

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Susan E. Freedman

Date of Signature: August 29, 2002

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Complete if Known

Application Number	09/997,586
Filing Date	November 28, 2001
First Named Inventor	Paul D. Franzon
Group Art Unit	2833
Examiner Name	Edwin A. Leon
Attorney Docket Number	5051-575

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Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.